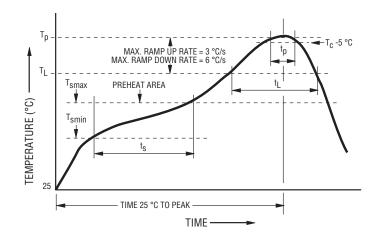


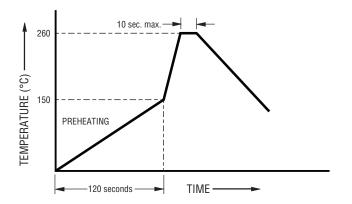
Solder Reflow Recommendations



Profile Feature	Pb-Free Assembly
Preheat / Soak:	
Temperature Min. (T _{smin})	150 °C
Temperature Max. (T _{smax})	200 °C
Time (t _s) from (T _{smin} to T _{smax})	60~120 seconds
Ramp Up Rate (T _L to T _p)	3 °C / second max.
Liquidous Temperature (T _L)	217 °C
Time (t _L) maintained above T _L	60~150 seconds
Peak Package Body	260 °C
Temperature (T _p)	
Time $(t_p)^*$ within 5 °C of the specified classification temperature (T_c)	30 seconds*
Ramp Down Rate (T _p to T _L)	6 °C / second max.
Time 25 °C to Peak Temperature	8 minutes max.

^{*} Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

Recommended Temperature Profile for Wave Soldering



Wave soldering is suitable for 1206 size models.

SF-1206HlxxxM Series - High Inrush Multilayer Surface Mount Fuses

BOURNS

